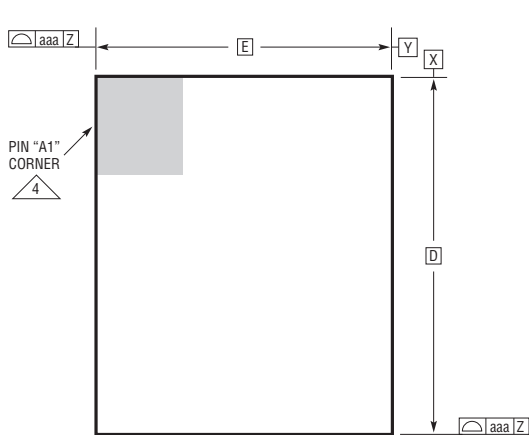
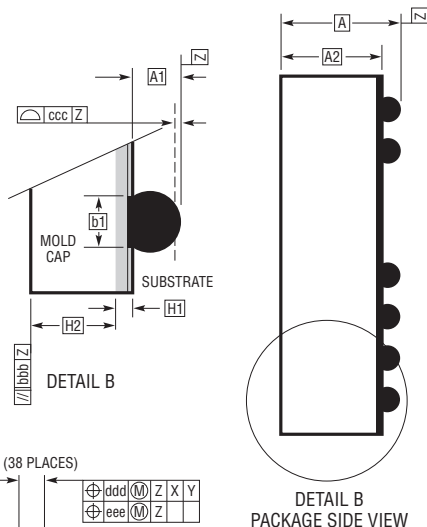


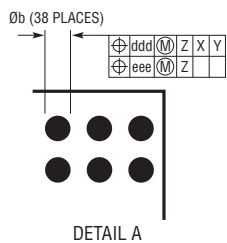
**BGA Package**  
**38-Lead (11.25mm × 9.00mm × 4.92mm)**  
 (Reference LTC DWG # 05-08-1925 Rev B)



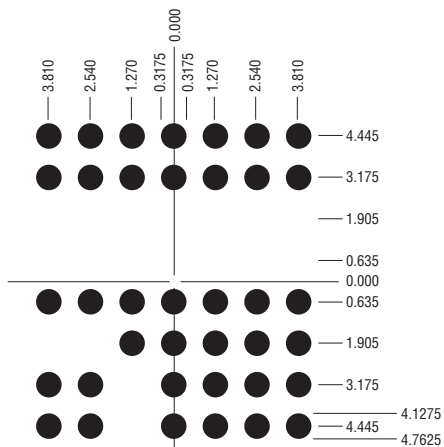
PACKAGE TOP VIEW



DETAIL B  
PACKAGE SIDE VIEW



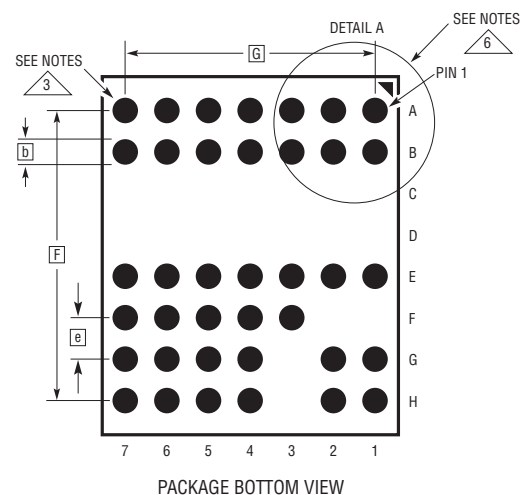
DETAIL A



SUGGESTED PCB LAYOUT  
TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	4.72	4.92	5.12	
A1	0.50	0.60	0.70	BALL HT
A2	4.22	4.32	4.42	
b	0.60	0.75	0.90	BALL DIMENSION
b1	0.60	0.63	0.66	PAD DIMENSION
D		11.25		
E		9.0		
e		1.27		
F		8.89		
G		7.62		
H1	0.27	0.32	0.37	SUBSTRATE THK
H2	3.95	4.00	4.05	MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.30	
eee			0.15	

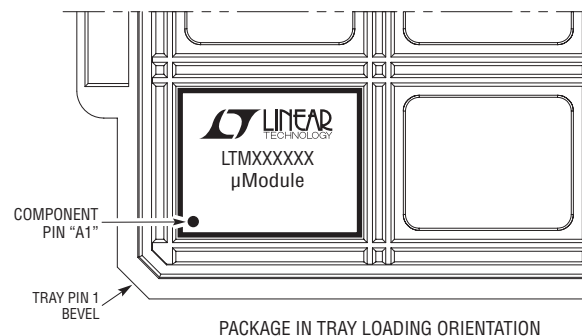
TOTAL NUMBER OF BALLS: 38



PACKAGE BOTTOM VIEW

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- ALL DIMENSIONS ARE IN MILLIMETERS
- BALL DESIGNATION PER JESD MS-028 AND JEP95
- DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
- PRIMARY DATUM -Z- IS SEATING PLANE
- PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG  $\mu$ Module PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION